

IN THE CLAIMS:

Claims 1 through 19 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

Listing of Claims:

1.-19. (Cancelled)

20. (Previously presented) A manufacturing method for a lead frame for a semiconductor assembly having a semiconductor device having two opposed peripheral sides, two opposed ends, an active surface in a first horizontal plane, a bottom inactive surface in a second horizontal plane, and a plurality of bond pads located on the active surface of the semiconductor device, a first portion of the plurality of bond pads located adjacent one of the two opposed peripheral sides and a second portion of the plurality of bond pads located adjacent another of the two opposed peripheral sides, said method comprising:
forming a first plurality of lead fingers extending substantially in the first horizontal plane of the active surface of the semiconductor device, each lead finger of the first plurality of lead fingers terminating in an end located adjacent a peripheral side of the two opposed peripheral sides of the semiconductor device;
forming a second plurality of lead fingers having portions thereof extending below the bottom inactive surface of the semiconductor device and having portions thereof extending in the first horizontal plane of said active surface of said semiconductor device, said second plurality of lead fingers having portions extending substantially inwardly and extending downwardly from said first horizontal plane of the active surface of the semiconductor device placing portions of said lead fingers in a second substantially horizontal plane for providing support surfaces for portions of said inactive surface of said semiconductor

device, each lead finger of the second plurality of lead fingers having a portion thereof extending adjacent an end of the two opposed ends of the semiconductor device and terminating in an end located adjacent the peripheral side of the two opposed peripheral sides of the semiconductor device, at least one lead finger of the second plurality of lead fingers including a section extending substantially in the first horizontal plane; and forming a die paddle for attaching portions of said inactive surface of said semiconductor device.

21. (Original) The method of claim 20, wherein the ends of the first plurality of lead fingers extend past the ends of adjacent lead fingers of the second plurality of lead fingers.

22. (Original) The method of claim 20, wherein the ends of the second plurality of lead fingers extend past the ends of adjacent lead fingers of the first plurality of lead fingers.

23. (Previously presented) The method of claim 20, further including:
placing tape on the second plurality of lead fingers.

24. (Previously presented) The method of claim 20, further including:
placing tape between the die paddle and the bottom inactive surface of the semiconductor device.

25. (Original) The method of claim 20, further including:
placing tape between the die paddle and the second plurality of lead fingers and the bottom inactive surface of the semiconductor device.

26. (Original) The method of claim 24, further comprising:
adhesively attaching the second plurality of lead fingers to the tape.

27. (Original) The method of claim 26, further comprising:
adhesively attaching the second plurality of lead fingers to the tape using thermosetting adhesive.

28. (Previously presented) The method of claim 20, wherein the die paddle includes at least one portion thereon extending beyond the peripheral side of the two opposed peripheral sides and at least another portion thereof extending beyond the end of the two opposed ends of the semiconductor device.

29. (Previously presented) The method of claim 20, wherein each lead finger of the second plurality of lead fingers includes an offset therein.

30. (Previously presented) The method of claim 20, wherein the second plurality of lead fingers includes:
at least one lead finger having a portion thereof extending adjacent a portion of a lead finger of the first plurality of lead fingers, a portion thereof extending substantially adjacent the end of the two opposed ends of the semiconductor device, a portion extending substantially opposed to the end of the two opposed ends of the semiconductor device, and having a portion extending beyond the peripheral side of the two opposed peripheral sides of the semiconductor device.

31. (Previously presented) The method of claim 20, wherein the second plurality of lead fingers includes:
at least one lead finger having a portion thereof extending adjacent a portion of a lead finger of the first plurality of lead fingers, a portion thereof extending substantially adjacent the end of the two opposed ends of the semiconductor device, a portion extending substantially opposed to the end of the opposed ends of the semiconductor device and extending adjacent a portion of the die paddle, and having a portion extending beyond the peripheral side of the two opposed peripheral sides of the semiconductor device.

IN THE DRAWINGS:

The attached drawing sheet includes changes to FIG. 1. This sheet replaces the original FIG. 1.

Specifically, FIG. 1 has been revised to delete both occurrences of reference numeral "16" with appropriate lead lines. No new matter has been added.